

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: T. Ho et al.
U.S.S.N.: Not Yet Assigned [Divisional of U.S. Serial No. 09/848,137]
FILED: Herewith
FOR: THERMALLY ENHANCED WAFER-LEVEL CHIP SCALE
PACKAGE AND METHOD OF FABRICATING THE SAME

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date November 21, 2003 in an envelope as "Express Mail Post Office to Addressee," mailing Label Number EV342589144US addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By: Michelle P. Chicos
Michelle P. Chicos

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PRELIMINARY AMENDMENT

Applicants kindly request that the above-identified application be amended as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks begin on page 5 of this paper.